

FORM PTO-1594
1-31-92

10-15-2001



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SHEET

U.S. Department of Commerce
Patent and Trademark Office
Attorney Docket No. 04202.0143

09/914448

To the Honorable Commissioner of
Please record the attached original

JCO3 Rec'd PTO 28 AUG 2001
ATTN. BOX ASSIGNMENTS

1. Name of conveying party(ies):

- 1) Shigeru KEMMOCHI
- 2) Mitsuhiro WATANABE
- 3) Tsuyoshi TAKETA
- 4) Hiroyuki TAI

08/28/01

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name

Other

Execution Date: August 20, 2001

2. Name and address of receiving party(ies):

Name: HITACHI METALS, LTD.

Internal Address:

Street Address: 2-1, Shibaura 1-chome, Minato-ku,
Tokyo, Japan

City:

State:

Zip Code:

Additional name(s) & Address(es) attached?

☐ Yes ☒ No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application: August 20, 2001

A. Patent Application Number(s):

08/30/2001 UEDUWIJE 00000155 09914448

05 FC:581

40.00 OP

B. Patent Number(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT
& DUNNER, L.L.P.

Street Address: 1300 I Street, N.W.

City: Washington

State: DC Zip: 20005-3315

6. Total number of applications and registrations involved:
1

7. Total fee (37 CFR 3.41): \$40
☒

Enclosed (Please charge deficiency to deposit account)
☐

Authorized to be charged to deposit account

8. Deposit account number: 06-0916

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman

Reg. No. 25,961

Signature

August 28, 2001

Date

Total number of pages including cover sheet, attachments and documents: 3

PATENT
REEL: 012235 FRAME: 0348

SOLE/JOINT INVENTION
(U.S. Rights Only)**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

HIGH-FREQUENCY SWITCH CIRCUIT, HIGH-FREQUENCY SWITCH MODULE AND
WIRELESS COMMUNICATIONS DEVICE COMPRISING IT

for which I/WE executed an application for United States Letters Patent concurrently herewith
or on _____ or filed an application for United States Letters Patent
on _____ (Serial No. _____); and

WHEREAS, HITACHI METALS, LTD., a corporation of Japan, whose post office address is
2-1, Shibaura 1-chome, Minato-ku, Tokyo, Japan

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

Sole or First Assignor

Full Name	Signature	Date
Shigeru KEMMOCHI	<i>Shigeru Kemmochi</i>	August 20, 2001
Address	Citizenship	
1-65, Beppu, Kumagaya-shi, Saitama-ken, Japan	Japan	

Second Assignor

Full Name	Signature	Date
Mitsuhiro WATANABE	<i>Mitsuhiro Watanabe</i>	August 20, 2001
Address	Citizenship	
74-6, Shin, Tottori-shi, Tottori-ken, Japan	Japan	

Third Assignor

Full Name	Signature	Date
Tsuyoshi TAKETA	<i>Tsuyoshi Taketa</i>	August 20, 2001
Address	Citizenship	
256 Machiya, Kokufu-cho, Iwami-gun, Tottori-ken, Japan	Japan	

Fourth Assignor

Full Name	Signature	Date
Hiroyuki TAI	<i>Hiroyuki Tai</i>	August 20, 2001
Address	Citizenship	
73, Matoba 2-chome, Tottori-shi, Tottori-ken, Japan	Japan	